

LAPLACE-FC

Laser Flip Chip Bonder



The LAPLACE-system provides an integrated solution for flip chip and capacitor/resistor attach. The laser assisted assembly is applied for soldering, ACF and NCP interconnections. The integrated dispensing unit in the flip chip assembly platform allows a maximal flexibility for flux, solder paste and/or ACF, NCP dispense.

LAPLACE is a solution for Smart Cards, Smart Label products, LCD-Drivers, Flip Chip on Flex and Flip Chip on Board application. Soldering and Curing of underfill is done by use of laser.

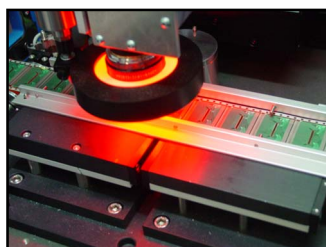
Specifications:

- Flip chip placement, reflow & curing in one step
- Fluxfree reflow with laser
- No additional reflow and curing
- Suitable for Flip Chip Soldering and adhesive Flip Chip: ACF, NCP, ICA
- Substrate materials:
 - PI, PVC, PE, Polyester
 - paper based low cost substrates
- In-Line capability
- High throughput
- Available with different accuracy specs [$\pm 5\mu\text{m}$, $\pm 10\mu\text{m}$, $\pm 25\mu\text{m}$]
- Vision system
- Temperature control unit
- Laser class I (IEC825, E DIN VDE 0750, 871, 837, CDRH)



Optional:

- Reel to Reel Unit
- Wafer Handling Systems



Pac Tech GmbH
Am Schlangenhorst 15-17
14641 Nauen
Germany

Tel: +49 (0)3321-4495-100
Fax: +49 (0)3321-4495-110
Email: sales@pactech.de

Pac Tech USA Inc.
328 Martin Avenue
Santa Clara, CA 95050
USA

Tel: +1 408-588-1925
Fax: +1 408-588-1927
Email: sales@pactech-usa.com

Pac Tech Asia Sdn. Bhd.
Plot 14, Medan Bayan Lepas
Technoplex, Phase 4
Bayan Lepas Industrial Zone
1190 Bayan Lepas, Penang
Malaysia

Tel: +60 19 47 83 760
Email: sales@pactech-asia.com

Pac Tech Thailand (Service Center)
98/286 Moo 9
Romruengarden vill Sol 5
Chiangragnoi, Ayutthaya 13160
Thailand

Tel: +66 899275852
Fax: +66 357422768
Email: customer.service@pactech-asia.com